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(54) **Coated cutting tool**

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Description

FIELD OF THE INVENTION

[0001] The present invention relates to a cutting tool for machining by chip removal comprising a substrate of cemented carbide, cermet, ceramics or high speed steel and a hard and wear resistant refractory coating. According to a preferred aspect, the coating is composed of one or more layers of refractory compounds of which at least one layer comprise a low compressive stress boride layer, e.g. TiB_2 or ZrB_2 , preferably TiB_2 , deposited by Physical Vapour Deposition (PVD). The TiB_2 and the rest of the layer(s), if any at all, are composed of metal nitrides and/or carbides and/or oxide with the metal elements chosen from Ti, Nb, Hf, V, Ta, Mo, Zr, Cr, W and Al.

BACKGROUND OF THE INVENTION

[0002] Industrial use of PVD TiB_2 layers has so far been strongly limited due to the very high compressive stresses normally possessed by such layers. In recent years large efforts have been made to develop PVD processes for deposition of new ultra-hard thin layers, e.g. boron carbide (B_4C), titanium diboride (TiB_2) and cubic boron nitride (c-BN), for wear protection, especially of cutting tools. Although these layer materials are very attractive for the tooling industry, they have not yet become commercialised.

[0003] The high hardness and Young's modulus of TiB_2 , as well as its chemical resistance, are attributed to the crystal structure and atomic bonding. In TiB_2 the Ti atoms form a metallic hexagonal structure. In analogy with the usual notation ABABAB for hexagonal close packing, the stacking sequence of Ti in TiB_2 will be AAA. The boron (B) atoms are situated interstitially between the A-layers forming a strong covalently bonded hexagonal net. The sequence may be described as AHAHAH where H denotes a boron layer. The combination of metallic Ti and strongly covalently bonded B results in a compound with high thermal and electrical conductivity as well as high yield strength and chemical resistance.

[0004] TiB_2 layers have been deposited by various PVD techniques, such as reactive sputtering, arc evaporation, and most commonly, magnetron sputtering. However, despite the very interesting properties of the TiB_2 bulk material, these layers are generally of little commercial interest. Their stress level is too high, which limits the practical adhesion, and thereby the layer thickness. In addition, due to the high intrinsic stressed layers are too brittle and easily fail because of lack of cohesion.

[0005] US 4,019,873 discloses a coated cemented carbide cutting tool insert. The coating is composed of two superimposed layers including an outer, extremely wear-resistant layer consisting essentially of aluminium oxide and/or zirconium oxide. The inner layer is composed of at least one boride selected from the group consisting of borides of the elements titanium, zirconium, hafnium, vanadium, niobium, tantalum, chromium, molybdenum and tungsten.

[0006] US 4,268,582 discloses a coated cemented carbide cutting tool insert comprising a cemented carbide substrate, the surface regions thereof having diffused therein an element such as boron, silicon or aluminium. The inserts further comprise a layer disposed on the diffused substrate, the layer being a boride such as titanium boride, hafnium boride, zirconium boride or tantalum boride. In another embodiment, the coated cemented article further includes an interlayer sandwiched between the diffused substrate and the boride layer.

[0007] Both these patents deposit the TiB_2 -layers by CVD. However, because of the high temperature during CVD-deposition undesirable cobaltboride-phases are formed. For that reason PVD deposition of TiB_2 -layers on WC-Co based substrates is preferred.

[0008] M. Berger, M. Larsson and S. Hogmark, Surf. Coat. Technol., 124 (2000) 253-261 have grown TiB_2 layers with magnetron sputtering using negative substrate bias varying from -220V to -50 V, the residual stress were very high (i.e. - compressive stress from -10.2 GPa to -7.9 GPa). Also, one variant using 0 V was grown also resulting in a very high compressive residual stress of -6.1 GPa. In this investigation no films were grown using positive bias.

[0009] C. Mitterer, M. Rauter and P. Rödhammer, Surf. Coat. Technol., 41 (1990) 351-363 have grown TiB_2 and Ti-B-N-C compound layers with magnetron sputtering using negative substrate bias. The TiB_2 layers were in high compressive residual stresses (\sim -4 GPa).

[0010] R. Wiedemann and H. Oettel, Surface Engineering, 14 4 (1998) 299-304 also have grown TiB_2 layers using magnetron sputtering. A negative substrate bias was used resulting in intrinsic compressive stress of \sim -2 GPa. The hardness was low (25-29 GPa).

[0011] One possibility to obtain a low compressive residual stress state boride layer would be, for example, to grow at a high pressure, or other condition reducing ion bombardment. However, this will give a layer with a columnar structure, often associated with grain boundaries that lack density, and a cauliflower shaped surface morphology. This microstructure is not preferable since a typical application of TiB_2 layers are, for example, machining of soft and sticky aluminium alloys, which require the coating of the cutting tool to have a very smooth top surface in order to reduce the tendency to form a build-up edge. Of course, grain boundaries that are not dense are detrimental for the wear-resistance of the coating.

SUMMARY OF THE INVENTION

[0012] It is an object of the present invention to provide a TiB₂-coated cemented carbide cutting tool insert.

[0013] It is a further object of the present invention to provide a method for depositing TiB₂ layers with low compressive residual stresses. The low stress TiB₂ layer should possess a dense, fibrous microstructure, and a smooth top-surface.

[0014] According to a first aspect, the present invention provides a cutting tool insert comprising a substrate and a coating, the coating comprising at least one layer of TiB₂ having a fibrous microstructure wherein the (cylindrical) grains are 5-50 nm, an average of approximately 15 nm in diameter and more than 250 nm long, with a length to diameter ratio $l/d > 2$, and the fibrous grains are oriented essentially perpendicularly to a surface of the substrate.

[0015] According to a second aspect, the present invention provides a method of making a cutting tool insert comprising a substrate and a coating including at least one layer of TiB₂ having a fibrous microstructure by PVD magnetron sputtering, the method comprising utilizing a bias voltage, $V_s > 0$ V.

BRIEF DESCRIPTION OF THE DRAWINGS

[0016]

Figure 1 is a photomicrograph of a cross-section of a relatively thin refractory layer formed according to the present invention.

Figure 2 is a photomicrograph of a cross-section of a relatively thick refractory layer formed according to the present invention.

Figure 3 is a schematic illustration of a magnetron sputtering device utilized in association with the present invention.

Figure 4 is a TEM micrograph of a relatively thin layer formed according to the principles of the present invention.

DETAILED DESCRIPTION OF THE INVENTION

[0017] In the following description the residual stress state, σ_{tot} , denote the total stress of a coating on the actual substrate, i.e. - the sum of the thermal stresses, $\sigma_{thermal}$, due to difference in coefficient of thermal expansion between the substrate and the coating material, and the intrinsic stresses, σ_{int} , originating from the actual growth process, i.e. -

$$\sigma_{tot} = \sigma_{thermal} + \sigma_{int}$$

[0018] Figure 1 shows the microstructure, in cross-section, of a relatively thin layer of TiB₂-layer (4 μ m), according to the present invention. Figure 2 is a corresponding picture of a thick layer (60 μ m). Figure 3 schematically shows the used magnetron sputtering equipment. Figure 4 shows a TEM micrograph layer of a thin layer (4 μ m).

[0019] In these figures S = substrate, P = pumping unit, M = magnetron, sputtering source, V_s = substrate potential (bias), I_s = substrate current, V_t = target potential, I_t = target current.

[0020] According to the present invention there is provided a cutting tool for machining by chip removal of materials such as non-ferrous material such as aluminium alloys. The cutting tool comprises a body of a hard alloy of cemented carbide, cermet, ceramics or high speed steel onto which a hard and wear resistant refractory coating is deposited. The wear resistant coating is composed of one or more layers of refractory compounds of which at least one layer, preferably the outermost layer, is composed of TiB₂, and that the innermost layer(s), if any at all, between the tool body and the TiB₂-layer, is composed of metal nitrides and/or carbides and/or oxides with the metal elements selected from Ti, Nb, Hf, V, Ta, Mo, Zr, Cr, W and Al. The TiB₂-layers are a dense, crystalline TiB₂ free of cracks with a fine-grained fibrous morphology described below.

[0021] The fine-grained fibrous TiB₂-layer can also be deposited directly onto a cutting tool substrate of cemented carbide, cermet, ceramics or high speed steel. The thickness of the TiB₂ layer(s) varies from 0.5 to 60 μ m preferably from 1 to 15 μ m, for metal machining. The total coating thickness according to the present invention varies from 0.5 to 60 μ m, preferably from 1 to 20 μ m, with the thickness of the non-TiB₂-layer(s) varying from 0.1 to 15 μ m. Further, layers of metal nitrides and/or carbides and/or oxide with the metal elements selected from Ti, Nb, Hf, V, Ta, Mo, Zr, Cr, W and Al can be deposited on top of the TiB₂-layer.

[0022] In an alternative embodiment, a process according to the present invention can be used to deposit layers thicker than 50 μ m with retained mechanical properties and adhesion to the substrate, due to the capability of the process capability to grow layers free of intrinsic stress.

[0023] In another alternative embodiment, thin layers (0.2 - 3 μ m) with an increased effective adhesion can be deposited.

[0024] In a preferred embodiment the TiB₂-layer is the outermost layer and with an average surface roughness R_a of not more than 50 nm.

[0025] This invention refers specially to a layer consisting of a fibrous morphology. PVD layers typically have a columnar morphology, i.e. - some grains have a tendency to increase in diameter on behalf of other grains. However, the TiB₂

layer according to present invention are grown in a mode where the fibrous morphology are kept almost unaffected from a layer thickness of 0.2 μm up to more than 60 μm . This morphology is in most cases preferable if a high cohesive strength of the grain boundaries are achieved. This is probably because of the small grain size in the direction of the abrasive wear, and large grain size in the direction of the applied compressive stress originating from the machining operation, giving a tougher coating material. Figure 1 shows a fracture cross-section of a relatively thin layer (4 μm) and Figure 2 shows a thick layer (60 μm). It is clearly evident that the morphology is almost unaffected by the layer thickness. Figure 4 shows a TEM micrograph layer of a thin layer (4 μm), that after the first fine grained nucleation zone, about 100 nm thick, the fibrous morphology develops. The cylindrical grains are typically 5-50 nm (in diameter), preferably 10-30 nm in average, 15 nm in diameter, and a length more than 250 nm, preferably more than 400 nm. The fibrous grains have a length to diameter ratio, $l/d > 2$, preferably > 5 , and d varies little over the main length of the grains. The fibers are oriented essentially perpendicularly to the surface of the substrate.

[0026] The fine-grained, fibrous crystalline TiB_2 according to the invention is strongly textured in the [001]-direction, a texture coefficient, TC, can be defined as.

$$\text{TC}(\text{hkl}) = \frac{I(\text{hkl})}{I_0(\text{hkl})} \left[\frac{1}{n} \sum_i^n \frac{I(\text{hkl})}{I_0(\text{hkl})} \right]^{-1}$$

where

$I(\text{hkl})$ = measured intensity of the (hkl) reflection

$I_0(\text{hkl})$ = standard intensity from the ASTM standard powder pattern diffraction data (JCPDS 35-0741)

n = number of reflections used in the calculation (in this case 8)

(hkl) reflections used are: (001), (100), (101), (110) (102 + 111), (201), (112) and (103 + 210). Where e.g. (103 + 210) means that those two, very close reflections, are treated as one reflection having the sum of intensity of the two. According to the present invention, the TC for the set of (001) crystal planes is greater than 5, preferably greater than 6.5.

[0027] In addition, TiB_2 -layers according to the present invention exhibit a residual stress state of $\sigma_{\text{tot}} < 0$ GPa but larger than -1 GPa, preferably -0.5 GPa, when deposited on WC- 6 wt% Co substrate. This corresponds to an intrinsic stress state, σ_{int} , close to zero. The thermal stresses, σ_{thermal} , can be calculated using

$$\sigma_{\text{thermal}} = \frac{E_f}{(1 - \nu_f)} \cdot (\alpha_f - \alpha_{\text{sub}}) \cdot (T_{\text{dep}} - T_{\text{ana}})$$

where E_f and ν_f are the Young's modulus and Poisson's ratio of the film, respectively. α_f and α_{sub} the coefficient of thermal expansion of the film and substrate material. T_{dep} and T_{ana} the deposition and analyse temperature in K. It is important to do the estimate of the thermal stresses by using the thermal expansion in the a-direction of the TiB_2 lattice, since due to the (001) texture almost all grains are oriented so that direction is parallel to the substrate surface. Using $\alpha_{\text{sub}} = 4.8 \cdot 10^{-6}$, $\alpha_{\text{TiB}_2, \text{a}} = 3.56 \cdot 10^{-6}$, $E_f = 600$ GPa, $\nu_f = 0.22$, $T_{\text{dep}} = 773$ K, $T_{\text{ana}} = 273$ K in the equation above gives $\sigma_{\text{thermal}} = -0.5$ GPa.

[0028] The residual stress, σ_{tot} , is determined using the well-known beam deflection technique.

[0029] The intrinsic stress can then be obtained by applying the equation:

$$\sigma_{\text{int}} = \sigma_{\text{tot}} - \sigma_{\text{thermal}}$$

[0030] The intrinsic stress, σ_{int} , of coatings deposited with positive bias is therefore:

$$\sigma_{\text{int}} = -0.5 - (-0.5) = 0 \text{ GPa,}$$

i.e. - those coatings are grown in a stress free mode.

[0031] According to the method of the present invention TiB_2 layers with low compressive residual stresses are deposited by magnetron sputtering of a TiB_2 target under the following conditions:

Magnetron power: 3 -20 kW

Substrate current I_s : -1 - -15 A

Atmosphere: Ar

Pressure: $<10^{-2}$ mbar, preferably $<10^{-3}$ mbar

Bias voltage V_s : >0 preferably $> +5$ V but $< +60$ V. The substrate current I_s changes polarity because of the positive V_s . This corresponds to low energetic ion bombardment and electron bombardment of the growing layer surface.

[0032] Layers deposited with the standard technology using negative V_s have a columnar structure. Here "columnar structure" describes a layer morphology where the grains, after the initially nucleation zone, have conical shape some with increasing diameter (in the plane parallel to the substrate surface), and other grains with decreasing diameter. This mode of growth is controlled by competition between different grains, where some grow out from others.

[0033] On the other hand, layers deposited with positive bias according to this invention consist of a fibrous morphology. No elements other than Ti, B, and small impurities of Ar are found in the layers, indicating that no sputtering from chamber walls occurs although the plasma potential probably is high when applying a positive potential.

[0034] While not intending to limit the invention to any particular theory, it is believed that the low stress level of layers according to the present invention is due to a combination of three effects: first, increased bulk temperature and adatom mobility; secondly, minimisation of energetic ion bombardment during growth; and thirdly, an electron bombardment of the surface enhancing surface mobility and increasing the nucleation rates. Also, is it likely that the electron current increases the desorption rate of absorbed hydrogen and/or water molecules from the surface. All this together result in drastically reduced residual stress compared to layers grown with negative substrate bias.

[0035] The residual stress state of layers grown according to present invention are almost free of intrinsic stress, i.e. - the slightly compressive stress state measured originate only from the difference in coefficient of thermal expansion between the substrate and the layer.

[0036] The present invention has been described with reference to TiB_2 -layers. It is obvious that the method can also be applied to the deposition of other wear resistant material where high compressive stresses is a problem such as ZrB_2 -layers or other borides.

Example 1

[0037] TiB_2 -layers were deposited in a commercially available deposition system aimed for thin film deposition equipped with a dc magnetron sputter source with a TiB_2 target ($12.5 \times 25.5 \text{ cm}^2$).

[0038] Mirror-polished cemented carbide substrates with composition 6 wt% Co and 94 wt% WC were used. The WC grain size was about $1 \mu\text{m}$ and the hardness was 1650 HV_{10} .

[0039] Before deposition, the substrates were cleaned in an ultrasonic bath of an alkali solution and in alcohol. The substrates were stationarily positioned 5 cm above the magnetron and resistively heated by an electron beam for 50 min to about 450°C . Immediately after heating, the substrates were argon-ion etched (ion current density 5.4 mA/cm^2) for 30 minutes using a substrate bias of -200V. The subsequent TiB_2 deposition was carried out at the following seven different bias voltages, V_s : -200V, -110V, +10V, +25V, +35V and +50V. A magnetron power of 6 kW, resulting in a target potential of about 500V and an Ar pressure of 3×10^{-3} mbar were maintained during deposition of all layers. The resulting thickness of the positively biased layers was $\sim 4 \mu\text{m}$. The negatively biased layers were made somewhat thinner ($\sim 3 \mu\text{m}$) to avoid layer failure due to their higher residual stresses. The substrate temperature was measured with a thermocouple attached to the substrate holder.

[0040] The substrate current I_s was +1.2 A for negative V_s , irrespective of voltage. When changing from negative to positive V_s the substrate current changed sign from positive to negative. The current was also found to increase with increasing positive V_s up to +25V whereafter it started to level of around 13 A for further V_s increase.

[0041] Using a positive V_s resulted in a substrate temperature at the end of deposition T_{dep} increase to about 200°C higher than using negative V_s . However, the different positive or negative V_s did not significantly influence T_{dep} .

[0042] XRD analysis showed that all films exhibited the hexagonal hcp- TiB_2 phase with a strong (001) texture with a texture coefficient as defined above of 6.5 or more, i.e. - no other diffraction peaks were detected. The FWHM values of the (001) peak showed that the positively biased layers gave sharper peaks than those formed with negative V_s . No

influence was seen on FWHM within the positive range of V_s , while for negative V_s , FWHM increased with the voltage.

[0043] SEM studies of fracture cross-sections revealed columnar structure for layers deposited with negative V_s . It was more pronounced for -200V than for -110V. For positive V_s , no columnar growth was observed. However, in higher magnification, a dense, fibrous morphology was observed on positively biased layers see Figure 1. EDS analysis indicated that all layers were slightly overstoichiometric in B. The Ti/B ratio was typically 0.46 for all layers independent of V_s . Layers grown with negative V_s contained as much as 8 at% Ar for $V_s = -200V$, while when using positive V_s no Ar could be detected. No other elements than Ti, B and Ar could be found in any layer.

[0044] By applying a positive V_s , independent of value, layers with low compressive residual stress states, $\sigma_{tot} \approx -0.5$ GPa, were obtained. This stress state corresponds roughly to the thermal stress state. On the other hand, using negative V_s gave layers with residual stresses in the range of -7 to -10 GPa.

[0045] All layers exhibited H and E values of about 50 and 600 GPa (measured with nanoindentation technique), respectively.

[0046] The abrasive wear rate was about 25-30 $\mu\text{m}^3/\text{mmN}$ for all layers, except the one grown with $V_s = -200V$ which showed about 50% higher wear rate than the other.

[0047] From a scratch test it was concluded that the adhesion was good for all layers, and in all cases the initial layer failure was of a cohesive type. There was no significant difference in critical load $F_{N,C}$ among the layers deposited with positive bias. They were all in the 42-46 N range. The layers deposited with negative V_s displayed a lower $F_{N,C}$, about 25-30 N, and also a higher amount of cohesive failures at the rim of the scratch, than layers deposited with positive V_s . Though, the scratch test demonstrate that coatings according to present invention have strongly enhanced toughness properties compared with coatings grown using negative bias.

[0048] The surface roughnesses, Ra, were measured with an interferometric method using a Wyco MD-2000 instrument. Of course will Ra of the coating be influenced by the surface roughness of the substrate for thin coatings, as in this example, here was Ra of the substrate ~ 5 nm. i.e. - the increase in Ra after deposition (~ 5 nm to ~ 20 nm) is extremely small. It is obvious that the surface roughness decreases when changing the substrate bias, V_s , from negative to positive see table 1. However, no significant difference between different coatings grown with different positive bias could be seen.

Table 1. Bias voltage and properties of the TiB_2 layers.

V_s [V]	FWHM (001) [2 θ]	σ [GPa]	H [GPa]	E [GPa]	$F_{N,C}$ [N]	Wear rate [$\mu\text{m}^3/\text{m mN}$]	Ra [nm]	Structure
-200V	0.495	10.5 ± 0.8	50 ± 5	605 ± 70	29 ± 1	61 ± 7	75	Columnar
-110V	0.453	7.1 ± 0.6	52 ± 3	600 ± 65	25 ± 1	32 ± 5	60	Columnar
+10V	0.287	0.5 ± 0.2	48 ± 4	580 ± 70	45 ± 1	26 ± 6	22	Fibrous
+25V	0.304	0.3 ± 0.2	49 ± 7	560 ± 95	43 ± 1	36 ± 8	18	Fibrous
+35V	0.286	0.7 ± 0.2	53 ± 7	640 ± 50	46 ± 3	32 ± 7	20	Fibrous
+50V	0.290	0.5 ± 0.2	54 ± 9	600 ± 85	42 ± 1	25 ± 3	15	Fibrous

Example 2

[0049] Cemented carbide cutting tool inserts, solid exchangeable end mill MM 16-20020-B120PF-M04 (WC-6 wt%Co) type were coated with a 30 μm thick layer of TiB_2 according to example 1 using a bias, V_s , of +50 V. The coated milling cutters were tested versus an uncoated variant of the same tool, in a copying milling operation of graphite, at 4000-6000 rpm, feed 700 mm/min

Variant	Tool life, h	Failure mode
Uncoated	10	Flank wear, Vbmax 0.3 mm
TiB_2 coated	40	Not end of tool life, Vbmax 0.1 mm

Example 3

[0050] Inserts coated with TiB_2 according to example 1 were tested. Coating of TiN (prior art) were compared with two different TiB_2 coated variants, deposited using V_s of -110 V and +50 V, respectively. Also an uncoated variant was

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tested. The cemented carbide insert had a polished rake face prior to coating. The edge hone was sharp. The carbide had a composition of 6.0 wt-% Co, 0.5 wt-% TaC/NbC, balance WC. The coating of the insert consisted of TiN or TiB₂ with a total thickness of 3.0 -4.0 μm.

Operation: Square shoulder milling
Work piece: Plate
Material: AA7075
Insert type: APEX160408FR-E08
Cutting speed: 800 m/min
Feed: 0.2 mm/rev
Depth of cut: 6.0 - 10.0 mm
Remarks: dry milling

Variant	Time at first formation of build-up edge(h)	Degree of build-up edge	Flank wear Vbmax (mm)
Uncoated	2.3	Heavy	0.18
TiN	1.1	Heavy	0.11
TiB ₂ (V _s = -110 V)	3.8	Small	0.05
TiB ₂ (V _s = +50 V)	6.2	None	Not measurable

Example 4

[0051] A similar procedure to example 3 was utilized but using a lower cutting speed in order to promote build-up edge formation.

Operation: Square shoulder milling
Work piece: Plate
Material: AA7075
Insert type: APEX160408FR-E08
Cutting speed: 650 m/min
Feed: 0.2 mm/rev
Depth of cut: 6.0 - 10.0 mm
Remarks: dry milling

Variant	Time at first formation of build-up edge (h)	Degree of build-up edge	Flank wear Vbmax (mm)
Uncoated	0.5	Very Heavy	0.21
TiN	Immediate	Very Heavy	0.18
TiB ₂ (V _s = -110 V)	4.0	Heavy	0.08
TiB ₂ (V _s = +50 V)	6.5	Small	Not measurable

Claims

1. A cutting tool insert comprising a substrate and a coating, the coating comprising at least one layer of TiB₂ having a fibrous microstructure **characterised in that** the cylindrical grains are 5-50 nm in diameter, more than 250 nm

long and with a length to diameter ratio $l/d > 2$, and the fibrous grains are oriented essentially perpendicularly to a surface of the substrate.

2. The cutting tool according to claim 1, **characterised in that** at least one TiB_2 -layer has a preferred growth orientation in the [001]-direction with a texture coefficient >5 defined as below:

$$TC(hkl) = \frac{I(hkl)}{I_0(hkl)} \left[\frac{1}{n} \sum_i \frac{I(hkl)}{I_0(hkl)} \right]^{-1}$$

where

$I(hkl)$ = measured intensity of the (hkl) reflection

$I_0(hkl)$ = standard intensity from the ASTM standard powder pattern diffraction data (JCPDS 35-0741)

n = number of reflections used in the calculation (in this case 8)

(hkl) reflections used are: (001), (100), (101), (110) (102 + 111), (201), (112) and (103 + 210).

3. The cutting tool according to claim 1, **characterised in that** the TiB_2 -layer exhibits an intrinsic stress state, σ_{int} , close to zero, i.e. - between +0.5 GPa and -1.0 GPa.
4. The cutting tool according to claim 1, **characterised in that** the TiB_2 layer is the outermost layer and has an average surface roughness R_a not more than 50 nm.
5. The cutting tool according to claim 1, **characterised in that** the cylindrical grains are 10-30 nm in diameter, more than 400 nm long and with a length to diameter ratio $l/d > 5$.
6. A method of making a cutting tool insert comprising a substrate and a coating including at least one layer of TiB_2 having a fibrous microstructure by PVD magnetron sputtering, **characterised in** the method comprising the use of a bias voltage, $V_s > 0$ V.
7. The method of claim 6, **characterised in that** the bias voltage is + 5V to +60V.

Patentansprüche

1. Schneidwerkzeugeinsatz, welcher ein Substrat und eine Beschichtung aufweist, wobei die Beschichtung zumindest eine Schicht aus TiB_2 aufweist, welche eine fasrige Mikrostruktur hat, **dadurch gekennzeichnet, dass** die zylindrischen Körner einen Durchmesser von 5-50 nm haben, mehr als 250 nm lang sind und ein Länge zu Durchmesser-Verhältnis $l/d > 2$ haben, und wobei die faserartigen Körner im Wesentlichen senkrecht zu einer Oberfläche des Substrates orientiert sind.
2. Schneidwerkzeug nach Anspruch 1, **dadurch gekennzeichnet, dass** zumindest eine TiB_2 -Schicht eine bevorzugte Wachstumsorientierung in der [001]-Richtung mit einem Texturkoeffizienten >5 hat, welcher nachstehend definiert ist:

$$TC(hkl) = \frac{I(hkl)}{I_0(hkl)} \left[\frac{1}{n} \sum_i \frac{I(hkl)}{I_0(hkl)} \right]^{-1}$$

wobei

$I(hkl)$ = gemessene Intensität des (hkl)-Reflexes

$I_0(hkl)$ = Standardintensität des Diagramms der Pulverdiffraktionsdaten nach ASTM-Standard ist (JCPDS

35-0741)

n = Anzahl der Reflexe ist, die in der Berechnung verwendet werden (im vorliegenden Fall 8), und die verwendeten (hkl)-Reflexe sind: (001), (100), (101), (110), (102+111), (201), (112) und (103+210).

3. Schneidwerkzeug nach Anspruch 1, **dadurch gekennzeichnet, dass** die TiB_2 -Schicht einen intrinsischen Spannungszustand σ_{int} zeigt, der nahe Null liegt, z. B. zwischen +0,5 GPa und -1,0 GPa.
4. Schneidwerkzeug nach Anspruch 1, **dadurch gekennzeichnet, dass** die TiB_2 -Schicht die äußerste Schicht ist und eine durchschnittliche Oberflächenrauheit R_a von nicht mehr als 50 nm hat.
5. Schneidwerkzeug nach Anspruch 1, **dadurch gekennzeichnet, dass** die zylindrischen Körner einen Durchmesser von 10-30 nm haben, mehr als 400 nm lang sind und ein Länge zu Durchmesser-Verhältnis $l/d > 5$ haben.
6. Verfahren zum Herstellen eines Schneidwerkzeuges, welches ein Substrat und eine Beschichtung aufweist, die zumindest eine Schicht aus TiB_2 mit einer fasrigen Mikrostruktur hat, durch PVD Magnetron-Sputtern, **dadurch gekennzeichnet, dass** das Verfahren die Verwendung einer Vorspannung von $V_s > 0$ V aufweist.
7. Verfahren nach Anspruch 6, **dadurch gekennzeichnet, dass** die Vorspannung +5 V bis +60 V beträgt.

Revendications

1. Un insert d'outil de coupe comprenant un substrat et un revêtement, le revêtement comprenant au moins une couche de TiB_2 ayant une microstructure fibreuse **caractérisé en ce que** les grains cylindriques sont d'un diamètre de 5 à 50 nm, de longueur supérieure à 250 nm et avec un rapport longueur/diamètre $l/d > 2$, et les grains fibreux sont orientés essentiellement perpendiculairement à une surface du substrat.
2. L'outil de coupe selon la revendication 1, **caractérisé en ce que** au moins une couche de TiB_2 a une orientation de croissance préférée selon la direction [001] avec un coefficient de texture, tel que défini par la formule ci-dessous, supérieur à 5, formule dans laquelle :

$$TC(hkl) = \frac{I(hkl)}{I_0(hkl)} \left[\frac{1}{n} \sum_1^n \frac{I(hkl)}{I_0(hkl)} \right]^{-1}$$

où

$I(hkl)$ = l'intensité mesurée de la réflexion (hkl)

$I_0(hkl)$ = l'intensité standard des données d'un spectre de diffraction de poudre selon la norme ASTM (JCPDS 35-0741)

n = le nombre de réflexions utilisé dans le calcul (dans ce cas 8)

les réflexions (hkl) utilisées sont : (001), (100), (101), (110) (102 + 111), (201), (112) et (103 + 210).

3. L'outil de coupe selon la revendication 1, **caractérisé en ce que** la couche de TiB_2 présente un état de contrainte intrinsèque σ_{int} proche de zéro, à savoir, compris entre + 0,5 GPa et - 1,0 GPa.
4. L'outil de coupe selon la revendication 1, **caractérisé en ce que** la couche de TiB_2 est la couche la plus externe et a une rugosité de surface moyenne R_a non supérieure à 50 nm.
5. L'outil de coupe selon la revendication 1, **caractérisé en ce que** les grains cylindriques sont de diamètre de 10 à 30 nm, de longueur supérieure à 400 nm et avec un rapport longueur/diamètre $l/d > 5$.
6. Un procédé de fabrication d'un insert d'outil de coupe comprenant un substrat et un revêtement incluant au moins une couche de TiB_2 ayant une microstructure fibreuse par pulvérisation à tube magnétron PVD, **caractérisé en ce que** le procédé comprend l'emploi d'une tension de polarisation, $V_s > 0$ V.

7. Le procédé selon la revendication 6, **caractérisé en ce que** tension de polarisation est comprise de + 5 V à + 60 V.

5

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Figure 1

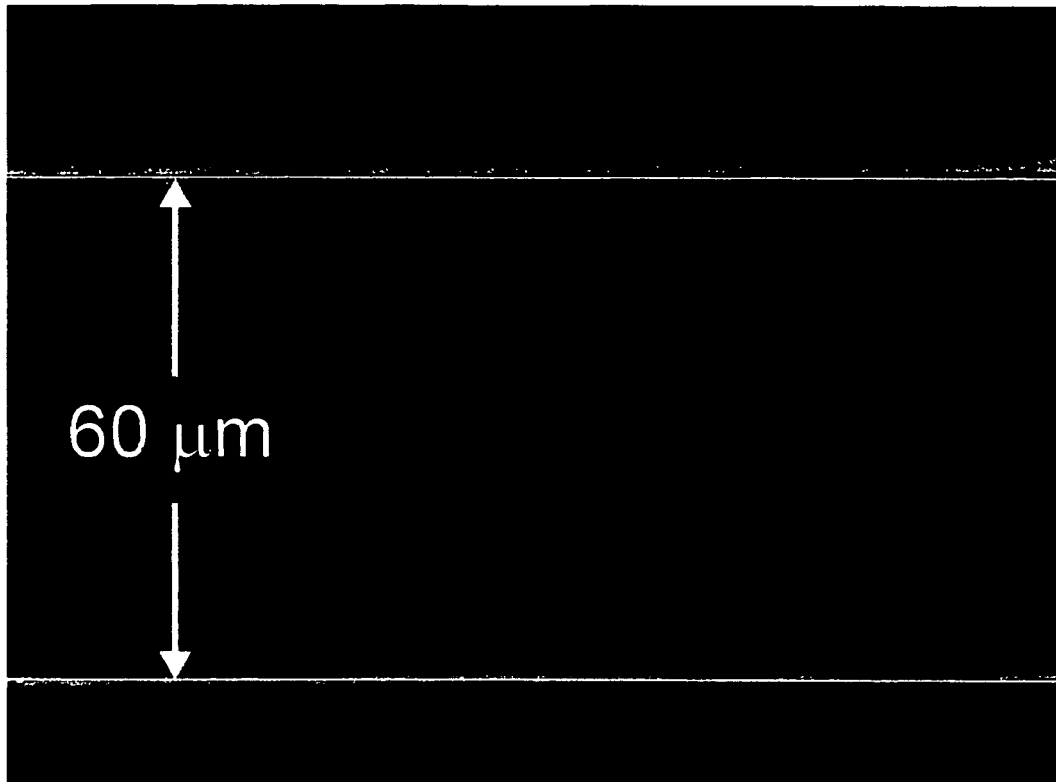


Figure 2

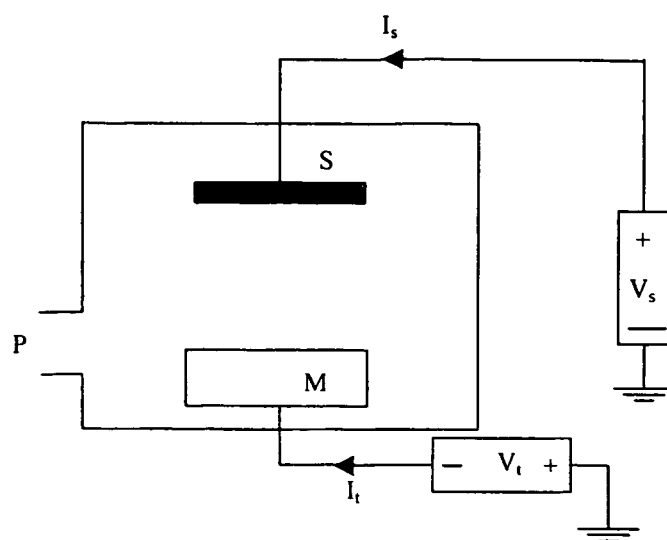


Figure 3

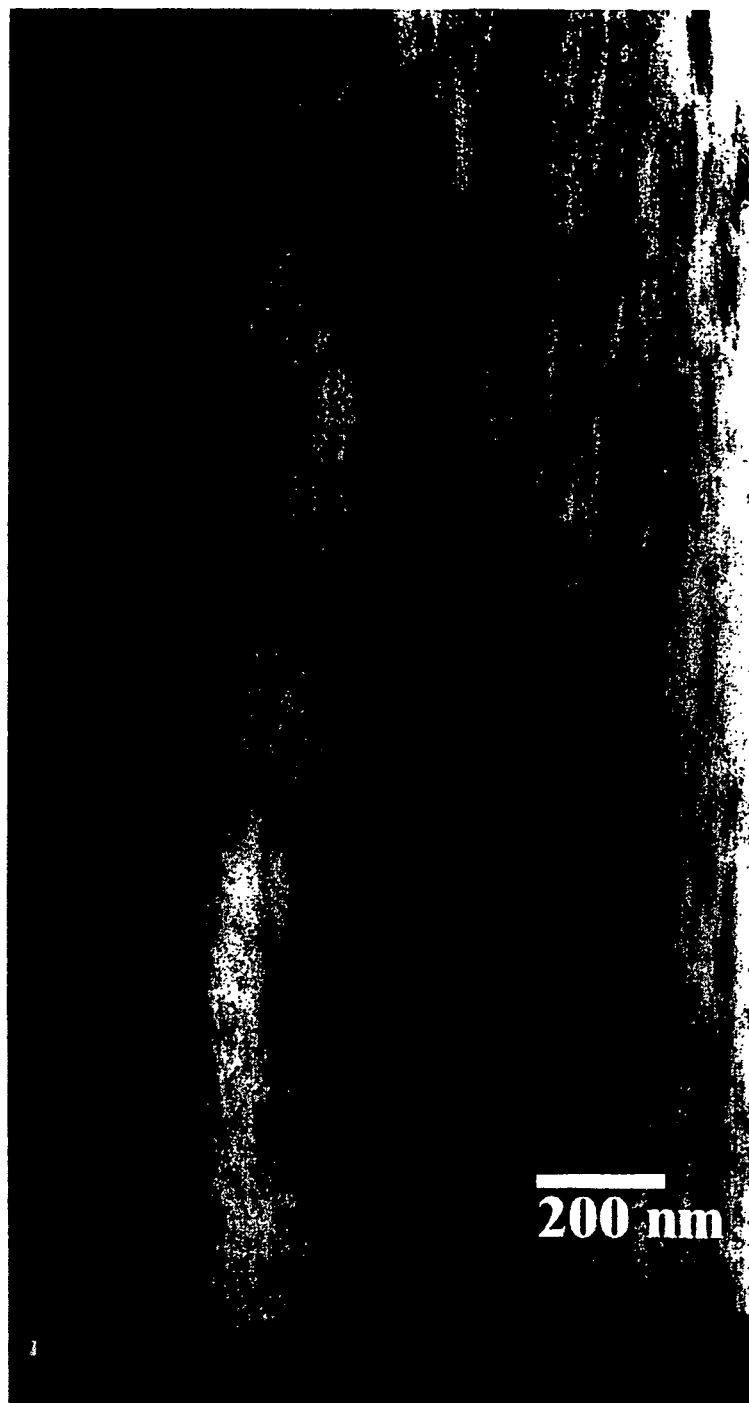


Figure 4

REFERENCES CITED IN THE DESCRIPTION

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